



NOTES:

1. Mfr. Telcom Semiconductor
2. Die size: .077 X .060 ±.005 Thickness: .010 minimum
3. Metallization: Topside - Al
4. Metallization: Backside (+Vcc) - Silicon (Backlapped)

FIGURE 3 - DIE CONFIGURATION (-002) FOR REFERENCE ONLY

CRANE interpoint 10301 WILLOWS ROAD, REDMOND, WA 98052	SIZE	CAGE NO.	DRAWING NO.	REV
	A	50821	84685	U
SCALE			SHEET 5 OF 10	